



FORM PTO-1449 (MODIFIED)

LIST OF PATENTS AND  
PUBLICATIONS  
FOR APPLICANTS INFORMATION  
DISCLOSURE STATEMENT

ATTORNEY DOCKET NO.

SP01-302

SERIAL NO.

10/035659

APPLICANT: COOK, et al.

FILING DATE 10/26/2001

GROUP: 1731

## REFERENCE DESIGNATION

## U.S. PATENT DOCUMENTS

Examiner Initial		Document Number	Date	Name	Class	Sub-Class	Filing Date if Approp.
	AA	4,186,999	2/5/80	Harwood et al	350	96.21	
	AB	4,530,452	7/23/85	Balyasny et al	225	96	
	AC	4,626,068	12/2/86	Caldwell	350	96.34	
	AD	5,183,710	2/2/93	Gerbino	428	405	
	AE	5,346,583	9/13/94	Basavanhally	156	629	
	AF	5,451,547	9/19/95	Himi et al	437	225	
	AG	5,452,122	9/19/95	Tsuneda et al	359	281	
	AH	5,579,421	11/26/96	Duvall et al	385	14	
	AI	5,631,986	5/20/97	Frey et al	385	78	
	AJ	5,846,638	12/8/98	Meissner	428	220	
	AK	5,852,622	12/22/98	Meissner et al	372	39	
	AL	5,989,372	11/23/99	Momoda et al	156	89.11	
	AM	6,030,883	2/29/00	Nishimoto et al	438	455	
	AN	6,048,103	4/11/00	Furukata et al	385	73	
	AO	6,249,619	6/19/01	Bergmann et al	385	11	
	AP	6,275,336	8/14/01	Yoshikawa et al	359	484	
	AQ	6,359,733	3/19/02	Iwatsuka et al	359	500	
	AR	6,583,029	6/24/03	Abe et al	438	455	
	AS	2002/0108556	8/15/02	Ebbers	117	2	
	AT	2003/0079503	5/1/03	Cook et al	65	407	
	AU	2003/0079823	5/1/03	Sabia	156	99	
	AV	2003/0081906	5/1/03	Filhaber et al	385	60	
	AW	2003/0206345	11/6/03	Sabia et al	359	484	
	AX	2003/0206347	11/6/03	Sabia et al	359	484	
	AY	2003/0081930	5/1/03	Filhaber et al	385	147	
	AZ	4,960,331	10/2/90	Goldman et al	356	350	
	AI	5,319,483	6/7/94	Krasinski et al	359	113	
	A2	5,441,803	8/15/95	Meissner	428	220	
	A3	5,689,519	11/18/97	Fermann et al	372	18	
	A4	6,120,917	9/19/00	Eda	428	692	
	A5	6,548,176	4/15/03	Gwo	428	420	
	A6	6,621,630	9/16/03	Iwatsuka	359	484	

05-2004

FORM PTO-1449 (MODIFIED)

ATTORNEY DOCKET NO.

SERIAL NO.

LIST OF PATENTS AND  
PUBLICATIONS  
FOR APPLICANTS INFORMATION  
DISCLOSURE STATEMENT

SP01-302

10/035659

APPLICANT: COOK, et al.

FILING DATE 10/26/2001

GROUP: 1731



## FOREIGN PATENT DOCUMENTS

		Document Number	Date	Country	Class	Sub-Class	Translation Yes      No
	AA	WO01/98225	12/27/01	PCT	C03C	27/06	
	AB	WO00/17698	3/30/00	PCT	G02F	1/09	
	AC	DE19731075	1/21/99	Germany	C03C	29/00	Relevance
	AD	DE2130905	1/11/73	Germany	H01j	19/56	Relevance?
	AE	08-146351	6/7/96	Japan (English Abstract)	G02B	27/28	
	AF	2002321947	4/25/01	Japan (English Abstract)	C03C	27/00	
	AH	03-115178	5/16/91	Japan (English Abstract)	C04B	37/00	

## OTHER ART (Including Author, Title, Date, Pertinent Pages, etc.)

	AI	ONISHI et al., "A novel temperature compensation method for SAW devices using direct bonding Techniques," <i>Ultrasonics Symp</i> , 1997, IEEE Proceedings, 5-8 Oct, 1997 Pages 227-230.	
	AK	Arthur Landrock; "Surface Preparation of Adherends"; <i>Adhesives Technology Handbook</i> , 1985; page 117-118	COPY Read - Poor quality

EXAMINER:

DATE CONSIDERED:

5-2004

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609: draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

**LIST OF PATENTS AND  
PUBLICATIONS  
FOR APPLICANTS INFORMATION  
DISCLOSURE STATEMENT**

APPLICANT Cook et al.

FILING DATE: Herewith GROUP: To Be Assigned

10/035659 U.S. PRO  
10/26/01**REFERENCE DESIGNATION****U.S. PATENT DOCUMENTS**

Examiner Initial		Document Number	Date	Name	Class	Sub-Class	Filing Date if Approp.
	AA	5,915,193	6/22/99	Tong et al.	438	455	
	AB	5,785,874	7/28/98	Eda	216	24	
	AC	5,932,048	8/3/99	Furukawa et al.	156	153	
	AD	6,129,854	10/10/00	Ramsey et al.	216	18	
	AE	6,153,495	11/28/00	Kub et al.	438	459	
	AF	6,178,779	1/30/01	Drouart et al.	65	391	
	AG	6,098,429	8/8/01	Mazabraud et al.	65	392	
	AH	4,407,667	10/4/83	LeNoane et al.	65	3.11	

**FOREIGN PATENT DOCUMENTS**

		Document Number	Date	Country	Class	Sub-Class	Translation Yes No
	AI	1 057 793A1	12/6/00	EPO	C03B	37/027	X

**OTHER ART (Including Author, Title, Date, Pertinent Pages, etc.)**

	AJ	A. Sayah, D. Solignac, T. Cueni, "Development of novel low temperature bonding technologies for microchip chemical analysis applications," Sensors and Actuators, 84 (2000) pp. 103-108. <i>Incomplete date</i>
	AK	P. Rangsten, O. Vallin, K. Hermansson, Y. Backlund, "Quartz-to-Quartz Direct bonding," J. Electrochemical Society, V. 146, N. 3, pp. 1104-1105, 1999).
	AL	H. Nakanishi, T. Nishimoto, M. Kani, T. Saitoh, R. Nakamura, T. Yoshida, S. Shoji, "Condition Optimization, Reliability Evaluation of SiO <sub>2</sub> -SiO <sub>2</sub> HF Bonding and Its Application for UV Detection Micro Flow Cell," Sensors and Actuators, V. 83, pp. 136-141, 2000. <i>In Complete date</i>
<i>Incomplete</i> <i>Log 101</i>	AM	A. Yamada, et al., Bonding Silieon wafer to Silicon Nitride With Spin-on Glass Adhesive, Electronics Letters, March 26, 1987, Vol. 23, No. 7.
	AN	D.J. Harrison, et al., Micromachining a Miniaturized Capillary Electrophoresis-Based Chemical Analysis System on a Chip, Science 261 (1993) 895-897.
	AO	W.P. Maszara, Silicon-on-insulator by Wafer Bonding: A Review, J. Electrochemical Society 138 (1991) 341-347.
	AP	D-W. Shin, et al., The Stacking Faults and Their Strain Effect at the Si/SiO <sub>2</sub> Interfaces of a Directly Bonded SOI (silicon on insulator), Thin Solid Films, V. 346, pp. 169-173, 1999.
	AQ	Q-Y. Tong, et al., The Role of Surface Chemistry in Bonding of Standard Silicon Wafers, J. Electrochemical Society V. 144, N. 1, pp. 384-389, 1997 <i>January</i>

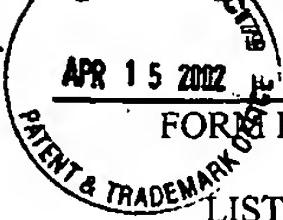
EXAMINER:

DATE CONSIDERED:

5-04

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609: draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

APR 15 2002



## FORM PTO-1449 (MODIFIED)

LIST OF PATENTS AND  
PUBLICATIONS  
FOR APPLICANTS INFORMATION  
DISCLOSURE STATEMENT

ATTORNEY DOCKET NO.

SP01-302

SERIAL NO.

10/035,659

APPLICANT Cook et al.

FILING DATE October 26, 2001

GROUP: To Be Assigned

## REFERENCE DESIGNATION

## U.S. PATENT DOCUMENTS

Examiner Initial		Document Number	Date	Name	Class	Sub-Class	Filing Date if Approp.
	AA						
	AB						
	AC						
	AD						
	AE						
	AF						
	AG						
	AH						
	AI						
	AJ						
	AK						

RECEIVED  
APR 17 2002  
TC 1700

## FOREIGN PATENT DOCUMENTS

		Document Number	Date	Country	Class	Sub-Class	Translation Yes	No
JH	AL	52[1977]-78450	7/1/77	Japan	G02B	5/14	X	
	AM							
	AN							
	AO							
	AP							
	AQ							

## OTHER ART (Including Author, Title, Date, Pertinent Pages, etc.)

AR	
AS	
AT	
AU	
AV	
AW	

EXAMINER:

DATE CONSIDERED:

5-2007

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609: draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

LIST OF PATENTS AND  
PUBLICATIONS  
FOR APPLICANT'S INFORMATION  
DISCLOSURE STATEMENT

SP01-302

10/035,659

APPLICANT Cook et al.

FILING DATE October 26, 2001

GROUP: 1731

## REFERENCE DESIGNATION

## U.S. PATENT DOCUMENTS

Examiner Initial	Document Number	Date	Name	Class	Sub-Class	Filing Date if Approp.
AA						
AB						
AC						
AD						
AE						
AF						
AG						
AH						
AI						
AJ						
AK						

## FOREIGN PATENT DOCUMENTS

	Document Number	Date	Country	Class	Sub-Class	Translation Yes No
AL						
AM						
AN						
AO						
AP						
AQ						

## OTHER ART (Including Author, Title, Date, Pertinent Pages, etc.)

<i>M</i>	AR	Andreas Piohl et al., Wafer Direct Bonding: Tailoring Adhesion Between Brittle Materials, Materials Science and Engineering, R25 (1999) pp. 1-88.
	AS	
	AT	
	AU	
	AV	
	AW	

EXAMINER:

DATE CONSIDERED:

*5-26-04*

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609: draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

FORM PTO-1449 (MODIFIED)

ATTORNEY DOCKET NO.

SERIAL NO.

LIST OF PATENTS AND  
PUBLICATIONS  
FOR APPLICANT'S INFORMATION  
DISCLOSURE STATEMENT

SP01-302

1P A0035,659

APPLICANT Cook et al.

NOV 06 2002

FILING DATE October 26, 2001

GROUP: 1731

## REFERENCE DESIGNATION

## U.S. PATENT DOCUMENTS

Examiner Initial		Document Number	Date	Name	Class	Sub-Class	Filing Date if Approp.
	AA						
	AB						
	AC						
	AD						
	AE						
	AF						
	AG						
	AH						
	AI						
	AJ						
	AK						

RECEIVED

NOV 07 2002

TC 1700

## FOREIGN PATENT DOCUMENTS

		Document Number	Date	Country	Class	Sub-Class	Translation Yes No
No copy of Patent Only a translator was SPM	AL	P2000-56265A	2/25/00	Japan	G02B	27/28	X
	AM						
	AN						
	AO						
	AP						
	AQ						

## OTHER ART (Including Author, Title, Date, Pertinent Pages, etc.)

AR	
AS	
AT	
AU	
AV	
AW	

EXAMINER:

DATE CONSIDERED:

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609: draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.